LSHM-DV SERIES

**HIGH SPEED HERMAPHRODITIC STRIP**

**SPECIFICATIONS**
For complete specifications and recommended PCB layouts see www.samtec.com/LSHM-DV

- **Insulator Material:** Black Liquid Crystal Polymer
- **Contact Material:** Phosphor Bronze
- **Plating:** Au or Sn over 50µ" (1,27 µm) Ni
- **Current Rating:** 1.3A per contact @ 95°C ambient
- **Operating Temp Range:** -55°C to +125°C
- **RoHS Compliant:** Yes
- **Processing:**
  - Lead-Free Solderable: Yes
  - SMT Lead Coplanarity: (0,10 mm) .004" max

**APPLICATION**

<table>
<thead>
<tr>
<th>NO. PINS</th>
<th>LEAD STYLE</th>
<th>PLATING OPTION</th>
<th>TAIL OPTION</th>
<th>SHIELD OPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>20, 30, 40, 50</td>
<td>-DV-</td>
<td>-F = Gold flash on contact, Matte Tin on tail</td>
<td>-S = With Shield</td>
<td>-TR = Tape &amp; Reel</td>
</tr>
<tr>
<td></td>
<td>-DV-N</td>
<td>-L =0.25&quot; (0.25 µm) Gold on contact, Matte Tin on tail</td>
<td>-N = Without Shield</td>
<td></td>
</tr>
<tr>
<td></td>
<td>-F</td>
<td>-DIA Polyimide film Pick &amp; Place Pad</td>
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**Mates with:** LSHM

- **High retention contacts**
- **Audible click when mated**
- **Shrouded**

**RUGGEDIZED**

- **High Speed/High Density**
- **Low cost Blade & Beam contact**

**LSHM-DV/LSHM-DV**

<table>
<thead>
<tr>
<th>Stack Height</th>
<th>Rated @ 3dB Insertion Loss*</th>
</tr>
</thead>
<tbody>
<tr>
<td>Single-Ended Signaling</td>
<td>11.5 GHz / 23 Gbps</td>
</tr>
<tr>
<td>Differential Pair Signaling</td>
<td>7 GHz / 14 Gbps</td>
</tr>
</tbody>
</table>

*Performance data includes effects of a non-optimized PCB. Performance data for other stack heights and complete test data available at www.samtec.com/LSHM-DV or contact sig@samtec.com

**Note:** Some lengths, styles and options are non-standard, non-returnable.

**Due to technical progress, all designs, specifications and components are subject to change without notice.**